

L Number	Hits	Search Text	DB	Time stamp
-	5	("5668057").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 15:57
-	0	pcb with semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 15:57
-	4	board with semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 15:59
-	2077	((printed adj circuit adj board) or (PCB)) and (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 18:14
-	440	((printed adj circuit adj board) or (PCB)) same (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:16
-	494	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) same (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 18:14
-	0	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) same (semiconductor adj substrate) and keypad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:19
-	0	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) same (semiconductor adj substrate)) and keypad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:20
-	38	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) and (semiconductor adj substrate)) and keypad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:33
-	9974	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) with (semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:35
-	8411	((printed adj (circuit or wiring)adj board)) with (semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:35
-	891	display and (((printed adj (circuit or wiring)adj board) or (PCB or pwc)) with (semiconductor) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:40
-	6667	display and (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:41

-	1013	display with (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:41
-	3844	(strain or pressure or keypad) with (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:42
-	20	(display with (semiconductor adj substrate)) and ((strain or pressure or keypad) with (semiconductor adj substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 16:47
-	12	substrate same display same (pressure or strain or keypad) same logic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:02
-	13555	touch adj panel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:02
-	5041	method and (touch adj panel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:03
-	1727	(pressure or strain) and (touch adj panel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:03
-	512	substrate and ((pressure or strain) and (touch adj panel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:11
-	2056	substrate and (gaas with light with emitting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:12
-	49270	substrate and ((gaas with light with emitting) or led)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:13
-	4878	(semiconductor adj substrate) and ((gaas with light with emitting) or led)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:14
-	106132	strain and (logic or control or computer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:15
-	29055	strain same (logic or control or computer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:16
-	29	((semiconductor adj substrate) and ((gaas with light with emitting) or led)) and (strain same (logic or control or computer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:28

-	3867	processor and strain and display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:54
-	169	processor same strain same display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:33
-	16	substrate and (processor same strain same display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:55
-	892	substrate and (processor and strain and display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:42
-	33527	processor and sensor and display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:55
-	47084	(microprocessor or processor) and sensor and display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:56
-	5896	substrate and ((microprocessor or processor) and sensor and display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 17:56
-	100	substrate with ((microprocessor or processor) and sensor and display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 18:13
-	1440	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) with silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 18:15
-	159	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) with silicon adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/11 18:16
-	9	((thermal or pressure or strain or chemical) with sensor) and (gaas with (junction or pn adj junction))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 15:27
-	20845	((thermal or pressure or strain or chemical) with sensor) and (display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 15:28
-	10529	((thermal or pressure or strain or chemical) with sensor) and (display) and (microprocessor or processor or logic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 15:30
-	2033	semiconductor and (((thermal or pressure or strain or chemical) with sensor) and (display) and (microprocessor or processor or logic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 15:31

750	substrate and (semiconductor and (((thermal or pressure or strain or chemical) with sensor) and (display) and (microprocessor or processor or logic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 15:52
31	common adj1 substrate and (semiconductor and (((thermal or pressure or strain or chemical) with sensor) and (display) and (microprocessor or processor or logic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 16:30
266	flannery.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:02
31	michael.in. and flannery.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:11
16354	(circuit adj board) with (silicon or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:16
132	(circuit adj board) with (silicon or semiconductor) adj (material or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:17
132	(circuit adj board) with ((silicon or semiconductor) adj (material or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:43
80	(display or lcd) same substrate same (microprocessor or logic) same (sensor or chemical or thermal or strain or microelectromechanical or micromechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:47
26	(display or lcd) same (semiconductor with substrate) same (microprocessor or logic) same (sensor or chemical or thermal or strain or microelectromechanical or micromechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 17:50
80608	sensor same (strain or thermal or chemically or chemical or radiation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:04
63307	display same (pixel or pixels)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:02
18416	(sensor same (strain or thermal or chemically or chemical or radiation)) and (microprocessor or processor or logic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:02
21881	(display same (pixel or pixels)) and (microprocessor or processor or logic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:03
3	(sensor same (strain or thermal or chemically or chemical or radiation)) same (display same (pixel or pixels)) same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:03

-	742	((sensor same (strain or thermal or chemically or chemical or radiation)) and (microprocessor or processor or logic)) and ((display same (pixel or pixels)) and (microprocessor or processor or logic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:04
-	91	wafer and (((sensor same (strain or thermal or chemically or chemical or radiation)) and (microprocessor or processor or logic)) and ((display same (pixel or pixels)) and (microprocessor or processor or logic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:04